

# Layer	Thickness	Description	Note
Top Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
Top Surface Finish	0.006mm		
1 Top Side	0.035mm	Starting foil 1/2oz. after plating and processing	
	0.125mm	Prepreg IPC-4101/21	FR-4.0
2 Inner Layer 1	0.017mm	ED Base Copper	
	0.410mm	Core IPC-4101/21	FR-4.0
3 Inner Layer 2	0.017mm	ED Base Copper	
	0.125mm	Prepreg IPC-4101/21	FR-4.0
4 Inner Layer 3	0.017mm	ED Base Copper	
	0.410mm	Core IPC-4101/21	FR-4.0
5 Inner Layer 4	0.017mm	ED Base Copper	
	0.125mm	Prepreg IPC-4101/21	FR-4.0
6 Inner Layer 5	0.017mm	ED Base Copper	
	0.410mm	Core IPC-4101/21	FR-4.0
7 Inner Layer 6	0.017mm	ED Base Copper	
	0.125mm	Prepreg IPC-4101/21	FR-4.0
8 Bottom Side	0.035mm	Starting foil 1/2oz. after plating and processing	
Bottom Surface Finish	0.006mm		
Bottom Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts

Total thickness: 1.943mm

notes:

Final copper thicknesses according to IPC-6012 **BASIC8_ML8_194_17_2V13**

Standard: Surface Finish ENIG
(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)

PCB Thickness Tolerance: ± 10%			
customer		created	
pcb name		approved	
engineer		format	A4, landscape
date			

Please follow our sectional design rules:
► www.we-online.com/designrulesbasic_en

For impedance matching stackups: Please consult our specialists: BASIC@we-online.com

Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen



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